Uddannelses- og
Forskningsministeriet

Chips JU Introduction Webinar

February 5th, 2025

Agenda

1. Welcome and introduction to Chips JU (UFM) - 5 min
2. Chips JU 2025 and other relevant Horizon Europe calls in 2025 (IFD) – 15 min
3. Sharing experiences from the Chips JU application process (AU/DkCCC) – 5 min
4. Q&A - 10 min
5. Introduction to Chips JU 2026/27 (to be discussed in detail at Follow-up Seminar) (DkCCC) - 5 min

Practical Information

We will share the slides with those joining today. The webinar will not be recorded.

Please write your questions in the Teams Q&A. We will answer as many questions as possible in the allocated time slot.

Please contact us may you still have any questions after the webinar (IFD, UFM, DkCCC)

EuroCenter - Agency for Higher Education and Science

National Contact Point (NCP) for Horizon Europe's Cluster 4 and Chips JU – counselling about opportunities, requirements and rules for applying

Representing Denmark in **Programme Committees** under Horizon Europe and **Chips JU's Public Authorities Board** - dialogue with Commission and Member States about structure and content of work programmes

European Chips Act

The European Chips act will bolster **EU's competitiveness and resilience** in semiconductor technologies and applications, and help achieve both the **digital and green transition.** It seeks to keep **Europe at the forefront of the technological development**, and **reduce dependencies**.

Three pillars: The Chips for EU Initiative, European Semiconductors Board, and Framework to ensure the security of supply.

Increase production capacity to 20% by 2030

In-depth understanding of the global semiconductor **supply chains**

Address the **skills shortage** and attract **new talent**

Strengthen research and technology leadership towards **smaller and faster chips**

Capacity to innovate in the **design, manufacturing and packaging** of advanced chips

Chips Joint Undertaking

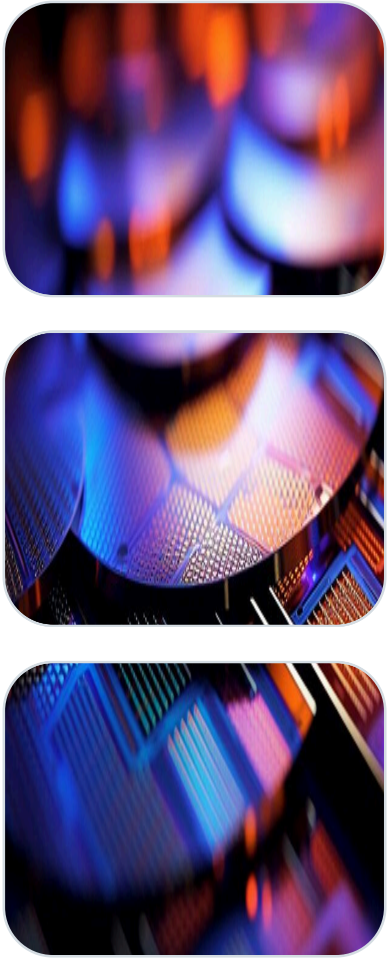
The objective is to **support technological capacity building and innovation in the EU,** by **bridging the gap between advanced research and innovation** capabilities and their industrial exploitation.

I. Setting up a **Design Platform**

II. Enhancing existing and developing new advanced **pilot lines**

III. Building capacities for accelerating the **development of quantum chips** and associated semiconductor technologies

IV. Establishing a **network of competence centers** across the EU



Mailing list

Purpose of the mailing list:

- Dissemination of **relevant Chips JU information**; e.g. funding opportunities, call deadlines, guidelines, work programmes etc.
- Share news of **relevant Chips JU events**

Sign up to the mailing list, by sending an mail to both **alel@ufm.dk** and **matu@ufm.dk** with the heading “Chips JU mailing list”

Please state your **full name/mail/organization or company**

Contact us!

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National Contact points

We provide guidance, practical information and assistance on all aspects of participation in Horizon Europe and Chips JU

eurocenter@ufm.dk
+45 3544 6240

Danish participation in Chips JU Calls 2021-2024

Danish participation in granted projects in Chips JU (2021-2024)

Calls 2021

- Global IA:
  - HICONNECTS: **Qtechnology A/s**
- RIA Focus Topic 1: Call on Edge AI, design stack and middleware
  - CLEVER: **AAU, Golfe ApS**

Calls 2022

- Global IA:
  - Arrowhead FPVN: **SDU, Soundfocus ApS**
  - ALL2GaN: **AAU, Blue World Technologies ApS**
- RIA Focus Topic 2: Call on Ecodesigned smart electronic systems
  - EECONE: **DTI, Melsen Tech A/S**

Calls 2023

- Global RIA:
  - VIVA: **NIL Technology ApS**
- IA Focus Topic 3: Call on Integration of trustworthy Edge AI
  - EdgeAI-Trust: **NVIDIA Denmark ApS, TEGnology ApS**
  - SMARTY: **NVIDIA dia Denmark ApS, Golfe ApS**
- CSA Call on Pan-European network for Advanced Packaging made in Europe)
  - Pack4EU**: ATLANT 3D ApS**

Calls 2024

- **5 projects with 11 Danish partners** selected for funding
- Grants under preparation

- RIA (Research & Innovation Action): Lower TRL (3-4)
- IA (Innovation Action) : Higher TRL (5-8)

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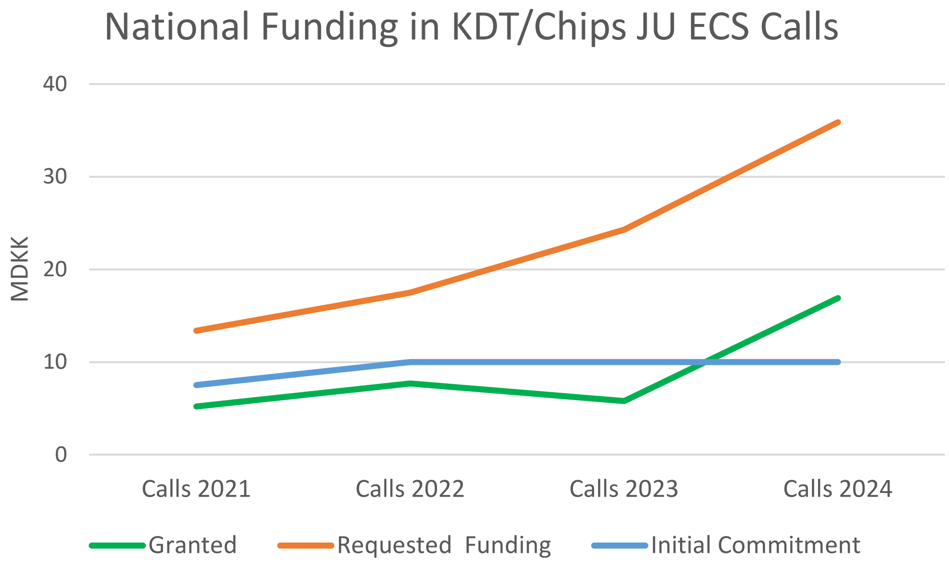
Danish participation in ECS Calls 2021-2024
Chips JU



- Growth trend in Danish participation
- We expect a similar funding situation for Chips JU ECS Calls 2025 as for ECS Calls 2024

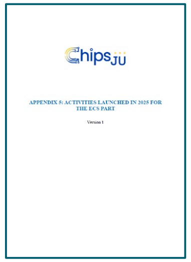
Chips JU
Work Programme 2025

Calls in Chips JU Work Programme 2025

Visit chips-ju.europa.eu, under ‘Documents’ for the latest version (NB.: frequently updated documents):

ECS Calls:

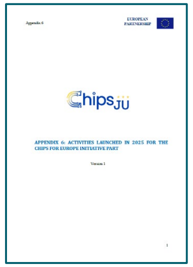
- ”MAWP – Appendix 5 - ECS”



Electronics Components and Systems (ECS) Calls 2025
(version 1, January 2025 - will be revised)

Chips for Europe Initiative Calls:

- ”MAWP – Appendix 6 – CEI”



Chips for Europe Initiative Calls 2025
(version 1, January 2025 - will be revised)

National rules and eligibility:

- Document: ”MAWP - General Annexes”

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Chips JU 2025

Calls with national co-funding

ECS Calls 2025 (5 calls)

Global Calls (bottom-up):

- **RIA** (ECS SRIA 2025) – 40 MEUR
- **IA** (ECS SRIA 2025) – 70 MEUR

2 Calls Focus Topics (IA):

- **RISC-V Automotive Hardware Platform** – 80 MEUR
- **AI-assisted Methods and Tools for Software-Defined Vehicle Engineering Automation** – 20 MEUR

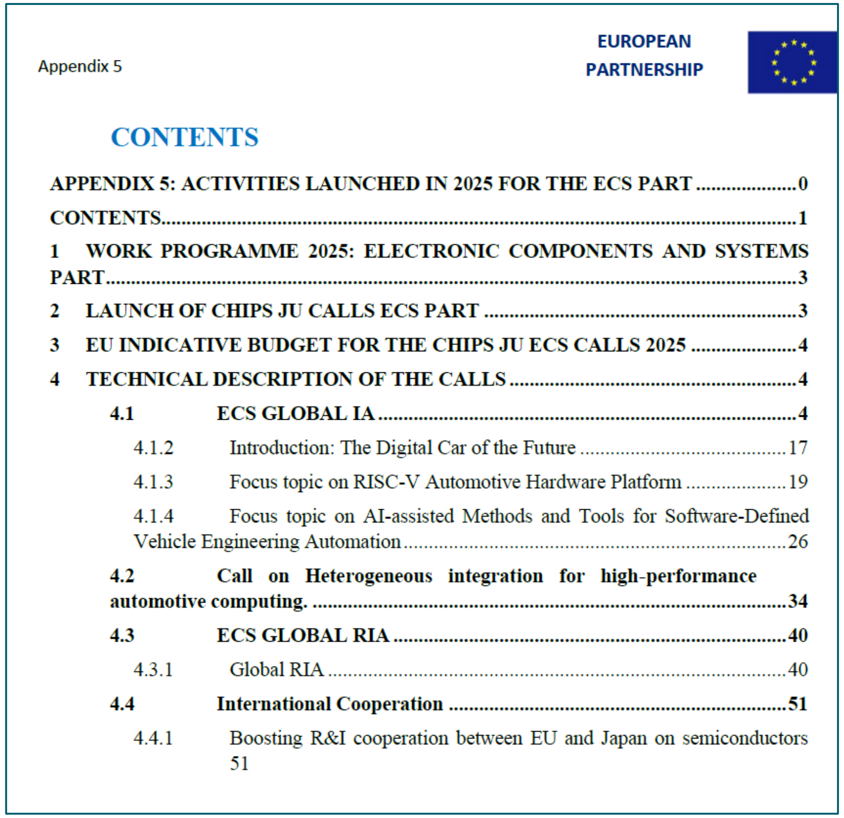
Call Launch: 4 March 2025
Deadlines:

- ✓ *Project Outline: 29 April 2025*
- ✓ *Full-proposal: 17 September 2025*

- **Call on Heterogeneous integration for high-performance automotive computing (IA)** – 20 MEUR

Call Launch: 4 March 2025
Deadlines:

- ✓ *Full-proposal: 29 April 2025 (one-stage call)*



Appendix 5

EUROPEAN
PARTNERSHIP

CONTENTS

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Chips for Europe Initiative Calls 2025

- **Open-source EDA tools development (IA)** – 20 MEUR

Call Launch: 4 March 2025
Deadlines:
  - ✓ *Project Outline: 29 April 2025*
  - ✓ *Full-proposal: 17 September 2025*

- **Low power Edge AI Chips (IA)*** – 20 MEUR
- **Accelerator for Advanced Strained Silicon on Insulator Substrates sSOI (IA)*** – 30 MEUR

Call Launch: 8 July 2025
Deadlines:
  - ✓ *Full-proposal: 17 September 2025 (one-stage calls)*

**Digital Europe rules apply for these calls*

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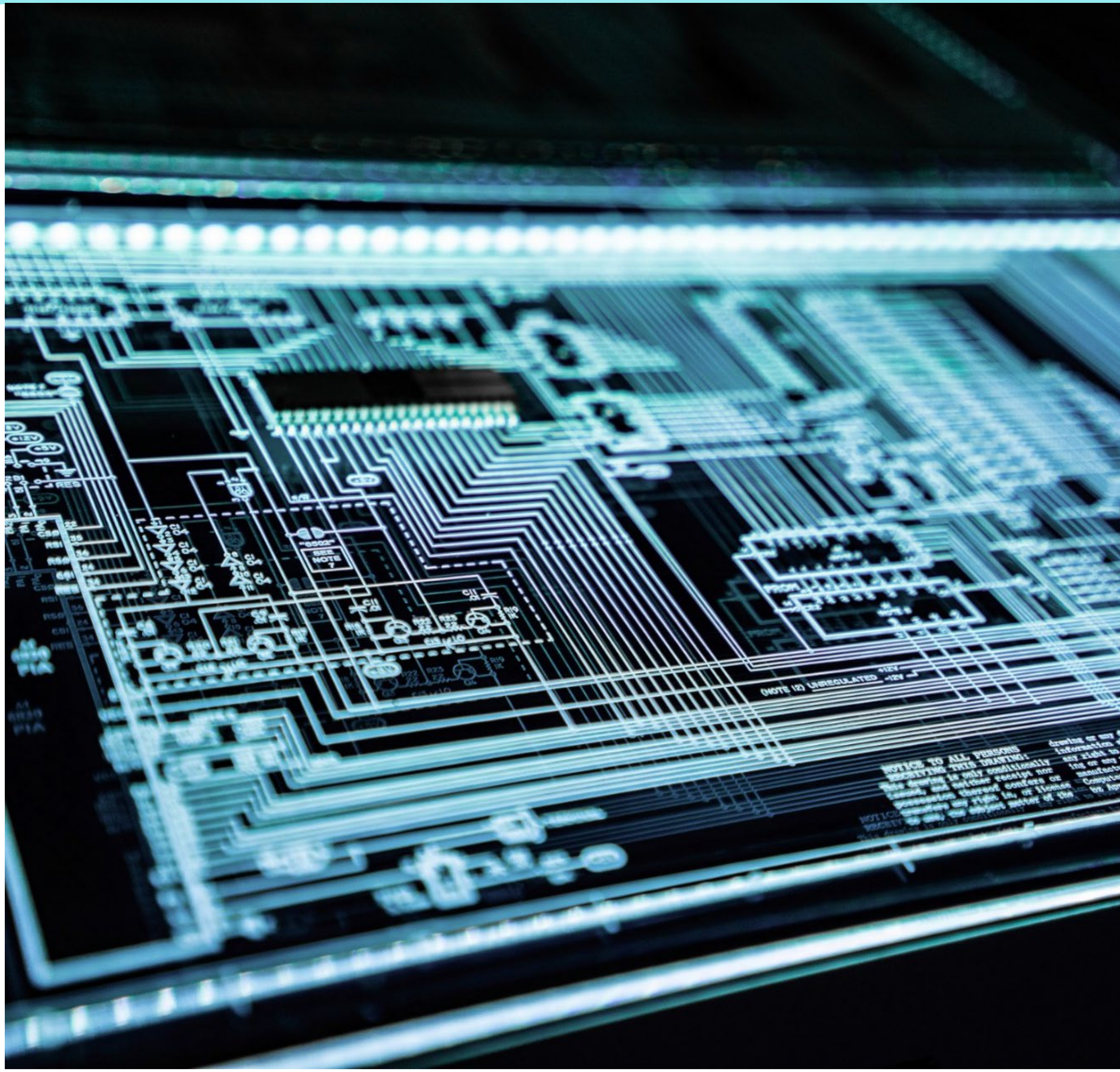
Quantum Pilot Lines

- ➢ A call for **additional quantum pilot lines** is foreseen in the WP2025 – *to be announced*

1. **The calls for first wave of quantum pilot lines are now closed - Framework Partnership Agreements (FPA)** (Work Program 2024)
2. The selected consortia will be eligible to apply to the Specific Grant Agreement (SGA) calls for **supporting developing Quantum Chip Technology**
    - **Stability Pilot Lines (RIA)** – 50 MEUR
    - **High-quality Trapped Ions Pilot Line (RIA)** – 25 MEUR

    Call timelines yet to be announced in 2025



Chips JU 2025

Calls only with EU funding

Other relevant calls with EU funding only

Chips for Europe Initiative Call:

- **A Pan-European infrastructure for Chips Design Innovation (CSA)** – 12 MEUR

Call Launch: 4 March 2025
Deadlines:
- ✓ *Full-proposal: 29 April 2025 (one-stage call)*

ECS Call:

- **Boosting R&I cooperation between EU and Japan on semiconductors (CSA)** – 1 MEUR

Call Launch: 8 July 2025
Deadlines:
- ✓ *Full-proposal: 17 September 2025 (one-stage call)*

Disclaimer: Only information on the IFD's Guidelines and the Work Program approved and published by Chips JU is valid. Changes may occur.

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Future calls and activities 2025/2026

Other Calls in WP2025 and future calls and activities

- **Design Platform**:
  - **Support for start-ups and SMEs** is foreseen at a later stage (2025/2026) – *TBD*
  - Calls for Design Enablement Teams (providers of chips design support services) to be launched in 2025 - *TBD*
- Call for **Lab-to-Fab Accelerators** is expected to be launched in 2025 or 2026 - *TBD*
- **Joint ECS Call with Japan** expected in 2026 - *TBD*

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How to apply to national co-funding

National co-funding for Calls 2025

- **Danish organisations** are eligible for national co-funding

- **Initial commitment** in national co-funding:
    - ECS Calls**:** 1.3 MEUR – *subject to the Research Reserve Agreement 2026*
    - Chips for Europe Initiative Calls: ca. 17 MEUR – *from Research Reserve Agreement 2025*

National co-funding limits:

- **Maximum**: 650 kEUR per project and per partner
    - ➢ *NB.: Not applicable for the calls for Quantum Pilot Lines*
- **Minimum**: 50 kEUR per partner

- **Maximum rates**: vary between 15-55% depending on the **specific call** and the **type of organisation** of the applicant

➢ *EU co-funding is added 'on top' of national co-funding. Specific rules apply to EU co-funding.*

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Example: SME applying to the Global IA Call

EU co-funding: 30% of eligible budget (according to EU rules)

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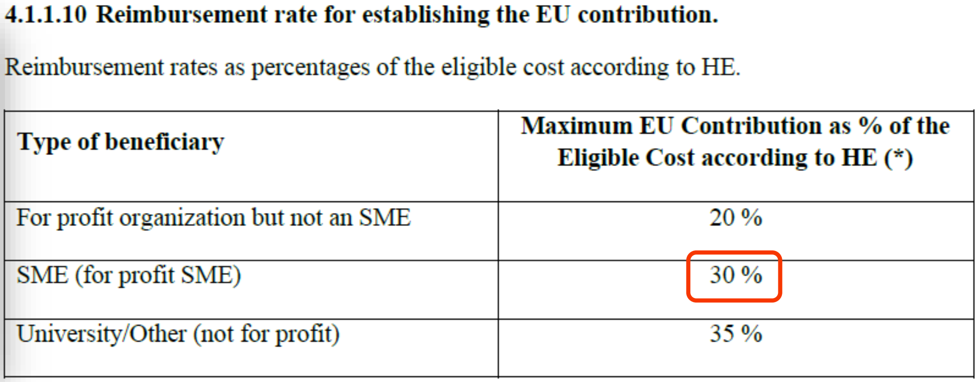
APPENDIX 5: ACTIVITIES LAUNCHED IN 2025 FOR THE ECS PART

Version 1



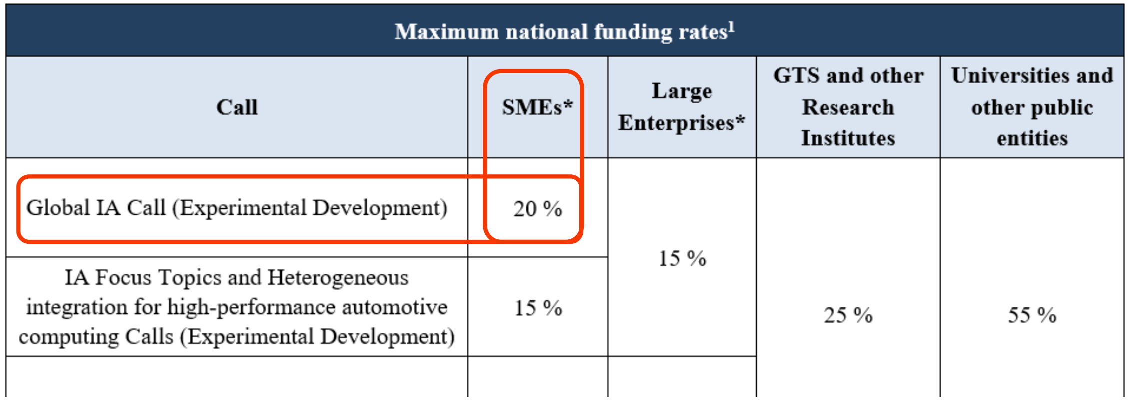
4.1.1.10 Reimbursement rate for establishing the EU contribution.

Reimbursement rates as percentages of the eligible cost according to HE.

Type of beneficiary	**Maximum EU Contribution as % of the Eligible Cost according to HE (*)**
For profit organization but not an SME	20 %
SME (for profit SME)	30 %
University/Other (not for profit)	35 %

- ➢ EU rules and conditions in the respective call text in the Chips JU WP2025

National co-funding: 20% of eligible budget (according to IFD's Guidelines)



Maximum national funding rates[1]				
Call	**SMEs***	**Large Enterprises***	**GTS and other Research Institutes**	**Universities and other public entities**
Global IA Call (Experimental Development)	20 %	15 %	25 %	55 %
IA Focus Topics and Heterogeneous integration for high-performance automotive computing Calls (Experimental Development)	15 %			

- ➢ "Country Specific Eligibility Rules" on MAWP General Annexes – *to be published by the launch of the calls*

✓ **Total funding:** 50%

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National process for application

You apply to the Chips JU Calls through the EU Portal with a common project proposal

For calls with national co-funding:

1. Follow IFD's national rules in the submitted proposal
2. No need to submit a proposal to IFD beforehand
3. IFD invites you via e-grant after the deadline
4. You are requested to provide mandatory documentation via e-grant

➢ *All templates for declarations can be found on IFD's website.*

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Other potential calls for you

Other relevant calls at IFD

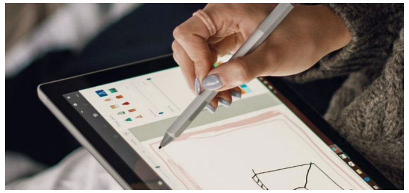
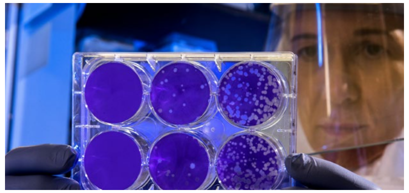
International Collaborations:

- **EUREKA Applied Quantum** Call 2 – opens Spring 2025
- **Eurostars** Call 8 – deadline 13 March 2025

- **Innobooster –** reopens for applications 4 March

- **Grand solutions 2025:**
  - Critical and Digital Technologies – deadline 19 March
  - Quantum Technologies – deadline 19 March

Reach out to IFD if you are interested in other funding opportunities.



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UFM: Other relevant calls with EU funding (Horizon Europe, Cluster 4)

- **Innovative solutions for the sustainable production for Semiconductor raw materials** (IA)

- **International cooperation in semiconductors** (CSA)

- **Microelectronics and photonics: Strengthening the fabless SME ecosystem in Europe** (CSA)

These calls are still in draft stage are expected to be published in April.

Reach out to Matthias Humer, matu@ufm.dk for more information.

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Website: International collaborations | Innovationsfonden

Innovation Fund Denmark

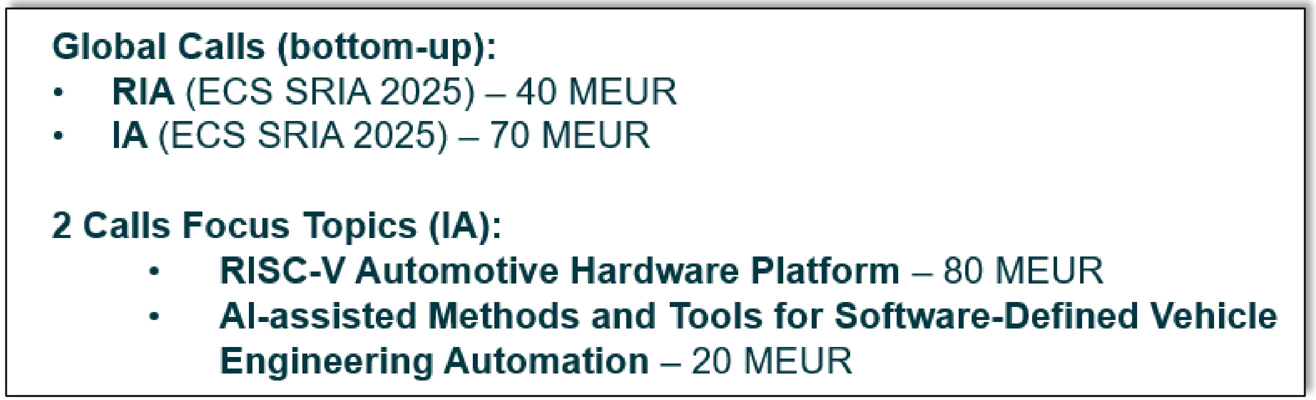
Horizon Webinar

Wednesday Feb. 5th 2025

Danish Chips
Competence
Centre

Seminar – Danish input to Chips JUs priorities 2026/2027

ECS Focus Topics 2025



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  - **RISC-V Automotive Hardware Platform** – 80 MEUR
  - **AI-assisted Methods and Tools for Software-Defined Vehicle Engineering Automation** – 20 MEUR

Possible Danish perspectives on Focus topics for 2026/27 is planned as a key element in the **follow-up seminar on February 21**.

- **Register for the Seminar:** [Chips JU follow-up seminar | Chips JU seminar]

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EU Competitive Compass – 3 pillars

1) Innovation

- AI
- Advanced materials
- Quantum
- Biotech
- Robotics
- Space technologies

2) Cleantech

- EU is the world leader in wind turbines, electrolysers and low-carbon fuels
- Green house gas monitoring
- Energy efficiency

3) Resilience

- Dual use technologies

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Thank you for your participation!

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